

## ISL9V5036P3\_F085

### EcoSPARK® 500mJ, 360V, N-Channel Ignition IGBT

#### General Description

The ISL9V5036P3\_F085 is the next generation IGBT that offer outstanding SCIS capability in the TO-220 plastic package. This device is intended for use in automotive ignition circuit, specifically as coil driver. Internal diode provide voltage clamping without the need for external component.

**EcoSPARK®** devices can be custom made to specific clamp voltages. Contact your nearest Fairchild sales office for more information.

Formerly Developmental Type 49443

#### Applications

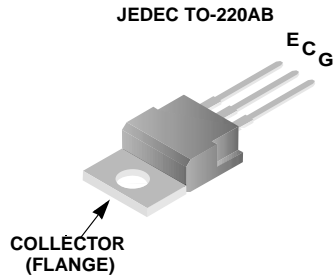
- Automotive Ignition Coil Driver Circuits
- Coil-On Plug Applications

#### Features

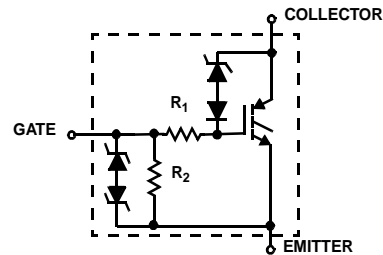
- Industry Standard TO-220 package
- SCIS Energy = 500mJ at  $T_J = 25^\circ\text{C}$
- Logic Level Gate Drive
- Qualified to AEC Q101
- RoHS Compliant



#### Package



#### Symbol



#### Device Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
$BV_{CER}$	Collector to Emitter Breakdown Voltage ( $I_C = 1 \text{ mA}$ )	390	V
$BV_{ECS}$	Emitter to Collector Voltage - Reverse Battery Condition ( $I_C = 10 \text{ mA}$ )	24	V
$E_{SCIS25}$	At Starting $T_J = 25^\circ\text{C}$ , $I_{SCIS} = 38.5\text{A}$ , $L = 670 \mu\text{H}$	500	mJ
$E_{SCIS150}$	At Starting $T_J = 150^\circ\text{C}$ , $I_{SCIS} = 30\text{A}$ , $L = 670 \mu\text{H}$	300	mJ
$I_{C25}$	Collector Current Continuous, At $T_C = 25^\circ\text{C}$ , See Fig 9	46	A
$I_{C110}$	Collector Current Continuous, At $T_C = 110^\circ\text{C}$ , See Fig 9	31	A
$V_{GEM}$	Gate to Emitter Voltage Continuous	$\pm 10$	V
$P_D$	Power Dissipation Total $T_C = 25^\circ\text{C}$	250	W
	Power Dissipation Derating $T_C > 25^\circ\text{C}$	1.67	W/ $^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-40 to 175	$^\circ\text{C}$
$T_{STG}$	Storage Junction Temperature Range	-40 to 175	$^\circ\text{C}$
$T_L$	Max Lead Temp for Soldering (Leads at 1.6mm from Case for 10s)	300	$^\circ\text{C}$
$T_{pkg}$	Max Lead Temp for Soldering (Package Body for 10s)	260	$^\circ\text{C}$
ESD	Electrostatic Discharge Voltage at 100pF, 1500 $\Omega$	4	kV

ISL9V5036P3\_F085 EcoSPARK® 500mJ,360V,N-Channel Ignition IGBT

**Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
V5036P	ISL9V5036P3_F085	TO-220AB	Tube	N/A	50

**Electrical Characteristics**  $T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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**Off State Characteristics**

$BV_{CER}$	Collector to Emitter Breakdown Voltage	$I_C = 2\text{mA}$ , $V_{GE} = 0$ , $R_G = 1\text{K}\Omega$ , See Fig. 15 $T_J = -40$ to $150^\circ\text{C}$	330	360	390	V	
$BV_{CES}$	Collector to Emitter Breakdown Voltage	$I_C = 10\text{mA}$ , $V_{GE} = 0$ , $R_G = 0$ , See Fig. 15 $T_J = -40$ to $150^\circ\text{C}$	360	390	420	V	
$BV_{ECS}$	Emitter to Collector Breakdown Voltage	$I_C = -75\text{mA}$ , $V_{GE} = 0\text{V}$ , $T_C = 25^\circ\text{C}$	30	-	-	V	
$BV_{GES}$	Gate to Emitter Breakdown Voltage	$I_{GES} = \pm 2\text{mA}$	$\pm 12$	$\pm 14$	-	V	
$I_{CER}$	Collector to Emitter Leakage Current	$V_{CER} = 250\text{V}$ , $R_G = 1\text{K}\Omega$ , See Fig. 11	$T_C = 25^\circ\text{C}$	-	-	25	$\mu\text{A}$
			$T_C = 150^\circ\text{C}$	-	-	1	mA
$I_{ECS}$	Emitter to Collector Leakage Current	$V_{EC} = 24\text{V}$ , See Fig. 11	$T_C = 25^\circ\text{C}$	-	-	1	mA
			$T_C = 150^\circ\text{C}$	-	-	40	mA
$R_1$	Series Gate Resistance		-	75	-	$\Omega$	
$R_2$	Gate to Emitter Resistance		10K	-	30K	$\Omega$	

**On State Characteristics**

$V_{CE(SAT)}$	Collector to Emitter Saturation Voltage	$I_C = 10\text{A}$ , $V_{GE} = 4.0\text{V}$	$T_C = 25^\circ\text{C}$ , See Fig. 4	-	1.17	1.60	V
$V_{CE(SAT)}$	Collector to Emitter Saturation Voltage	$I_C = 15\text{A}$ , $V_{GE} = 4.5\text{V}$	$T_C = 150^\circ\text{C}$	-	1.50	1.80	V

**Dynamic Characteristics**

$Q_{G(ON)}$	Gate Charge	$I_C = 10\text{A}$ , $V_{CE} = 12\text{V}$ , $V_{GE} = 5\text{V}$ , See Fig. 14	-	32	-	nC	
$V_{GE(TH)}$	Gate to Emitter Threshold Voltage	$I_C = 1.0\text{mA}$ , $V_{CE} = V_{GE}$ , See Fig. 10	$T_C = 25^\circ\text{C}$	1.3	-	2.2	V
			$T_C = 150^\circ\text{C}$	0.75	-	1.8	V
$V_{GEP}$	Gate to Emitter Plateau Voltage	$I_C = 10\text{A}$ , $V_{CE} = 12\text{V}$	-	3.0	-	V	

**Switching Characteristics**

$t_{d(ON)R}$	Current Turn-On Delay Time-Resistive	$V_{CE} = 14\text{V}$ , $R_L = 1\Omega$ , $V_{GE} = 5\text{V}$ , $R_G = 1\text{K}\Omega$ , $T_J = 25^\circ\text{C}$ , See Fig. 12	-	0.7	4	$\mu\text{s}$
$t_{rR}$	Current Rise Time-Resistive		-	2.1	7	$\mu\text{s}$
$t_{d(OFF)L}$	Current Turn-Off Delay Time-Inductive	$V_{CE} = 300\text{V}$ , $L = 2\text{mH}$ , $V_{GE} = 5\text{V}$ , $R_G = 1\text{K}\Omega$ , $T_J = 25^\circ\text{C}$ , See Fig. 12	-	10.8	15	$\mu\text{s}$
$t_{fL}$	Current Fall Time-Inductive		-	2.8	15	$\mu\text{s}$
SCIS	Self Clamped Inductive Switching	$T_J = 25^\circ\text{C}$ , $L = 670\mu\text{H}$ , $R_G = 1\text{K}\Omega$ , $V_{GE} = 5\text{V}$ , See Fig. 1 & 2	-	-	500	mJ

**Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance Junction-Case	-	-	0.6	$^\circ\text{C/W}$
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Typical Characteristics

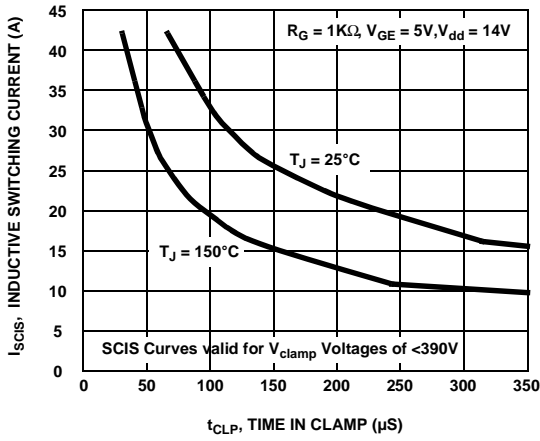


Figure 1. Self Clamped Inductive Switching Current vs Time in Clamp

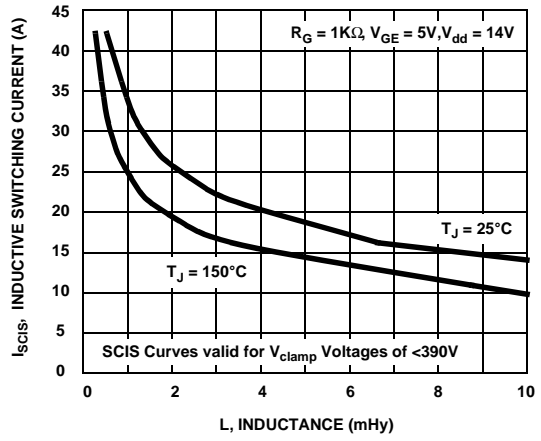


Figure 2. Self Clamped Inductive Switching Current vs Inductance

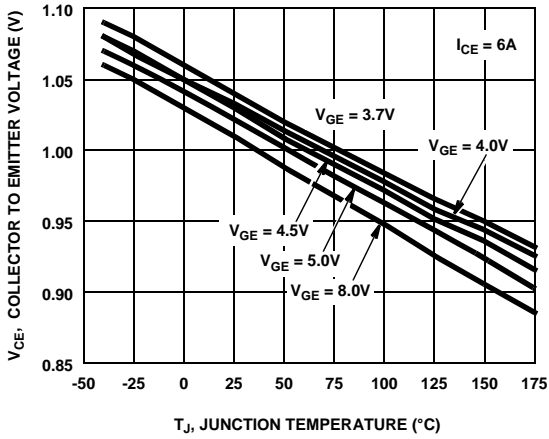


Figure 3. Collector to Emitter On-State Voltage vs Junction Temperature

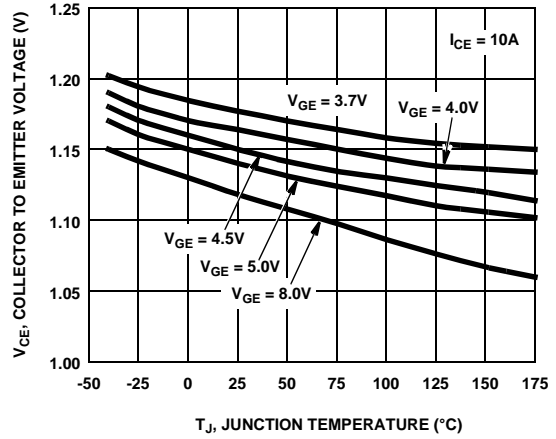


Figure 4. Collector to Emitter On-State Voltage vs Junction Temperature

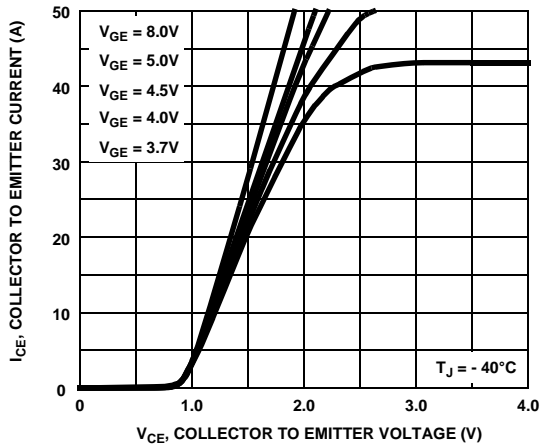


Figure 5. Collector Current vs Collector to Emitter On-State Voltage

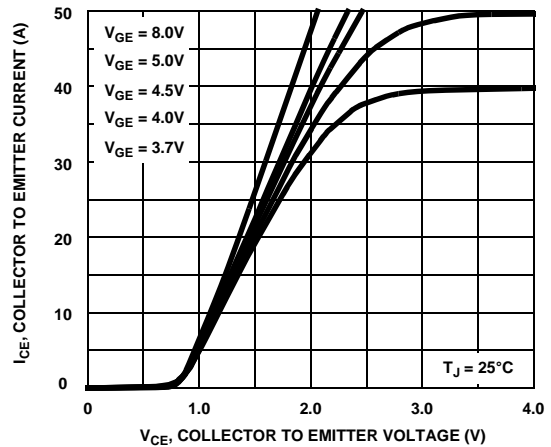


Figure 6. Collector Current vs Collector to Emitter On-State Voltage

Typical Characteristics (Continued)

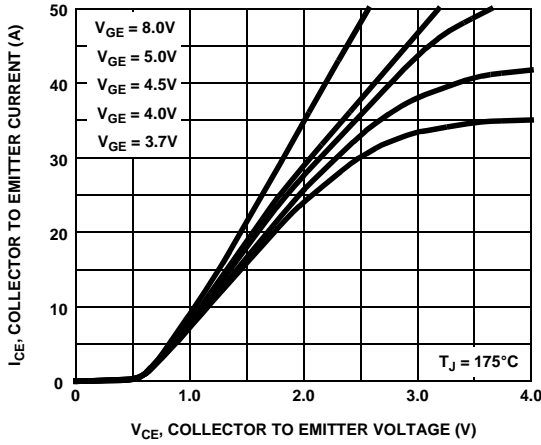


Figure 7. Collector to Emitter On-State Voltage vs Collector Current

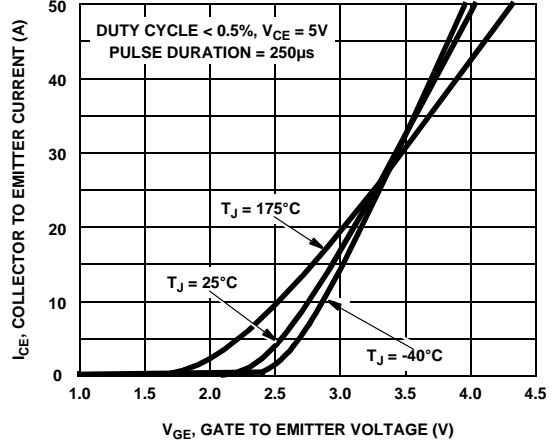


Figure 8. Transfer Characteristics

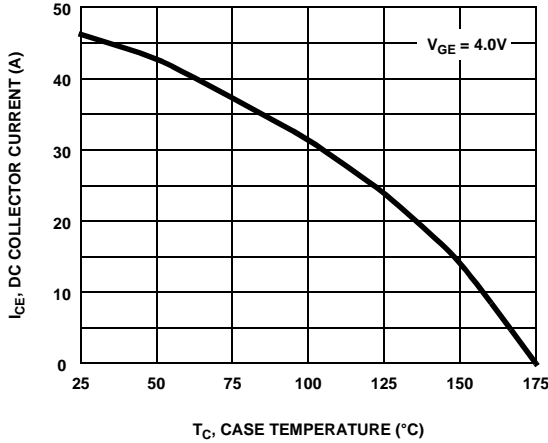


Figure 9. DC Collector Current vs Case Temperature

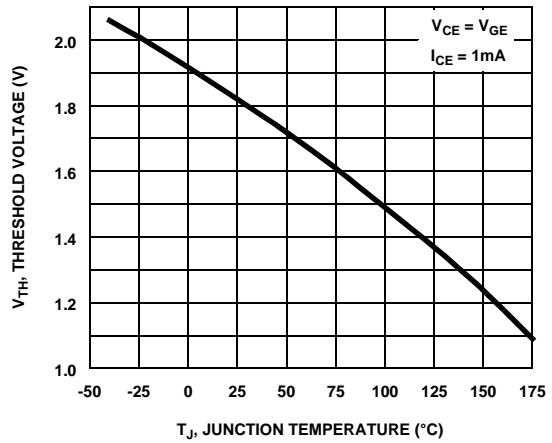


Figure 10. Threshold Voltage vs Junction Temperature

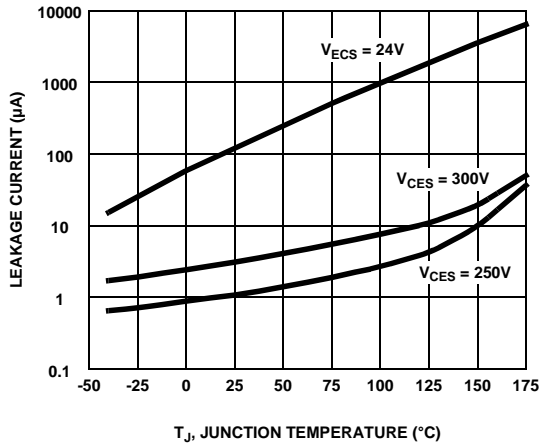


Figure 11. Leakage Current vs Junction Temperature

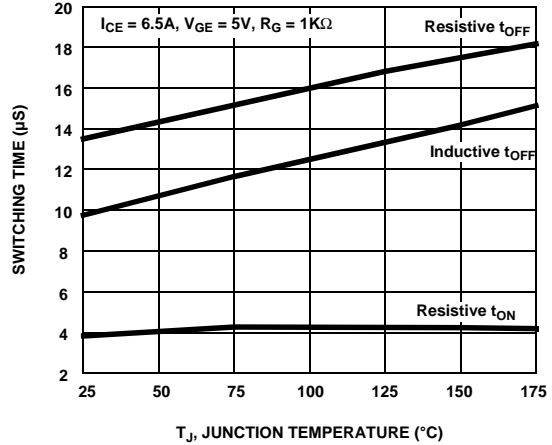
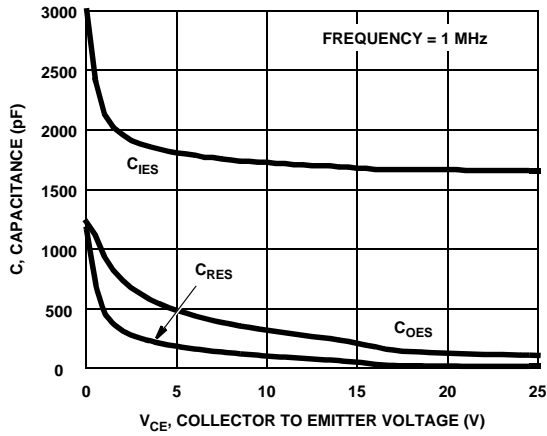
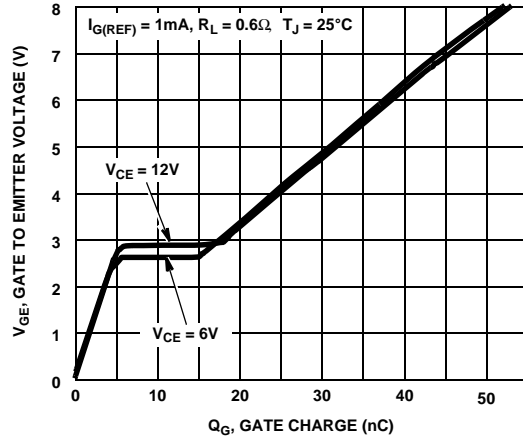


Figure 12. Switching Time vs Junction Temperature

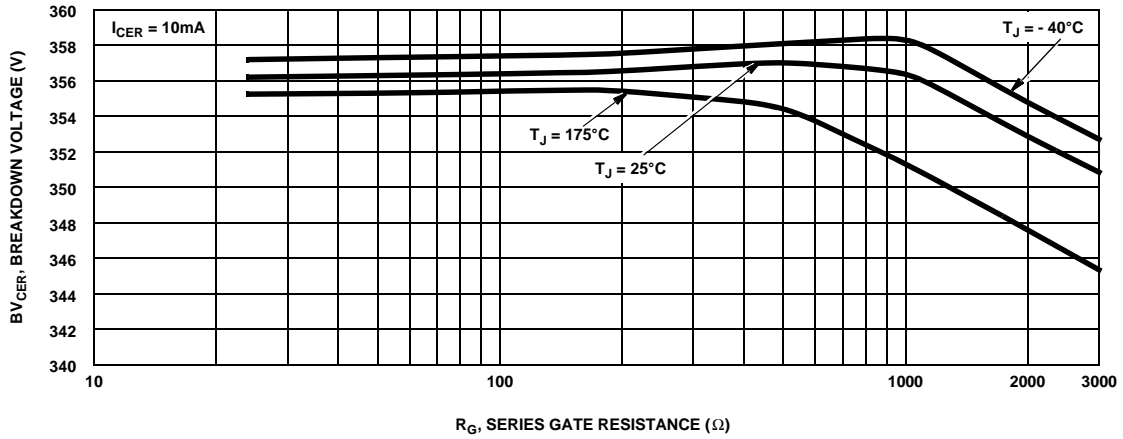
**Typical Characteristics** (Continued)



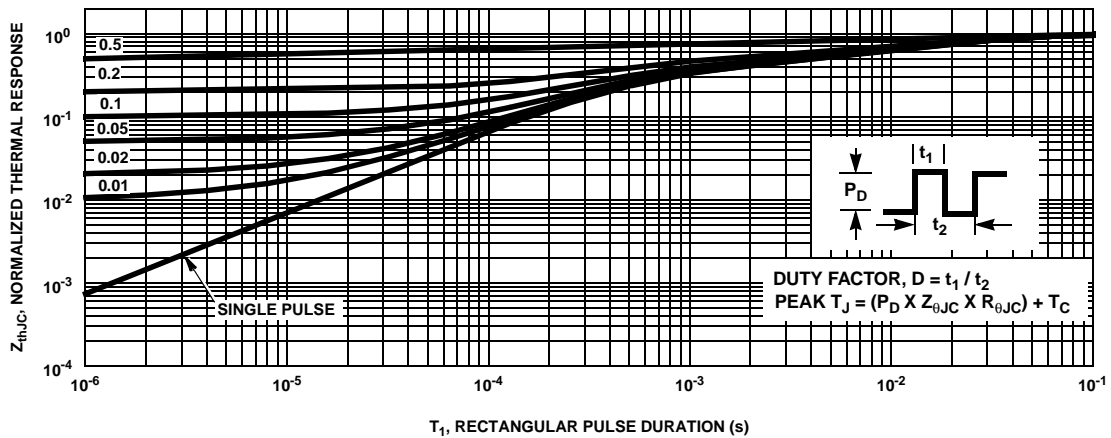
**Figure 13. Capacitance vs Collector to Emitter Voltage**



**Figure 14. Gate Charge**



**Figure 15. Breakdown Voltage vs Series Gate Resistance**



**Figure 16. IGBT Normalized Transient Thermal Impedance, Junction to Case**

Test Circuits and Waveforms

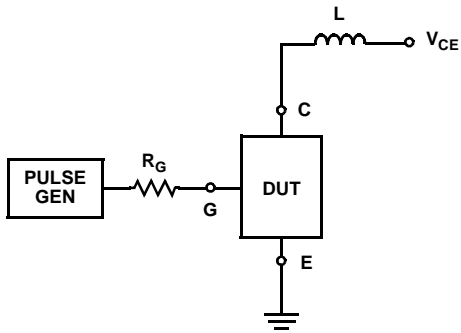


Figure 17. Inductive Switching Test Circuit

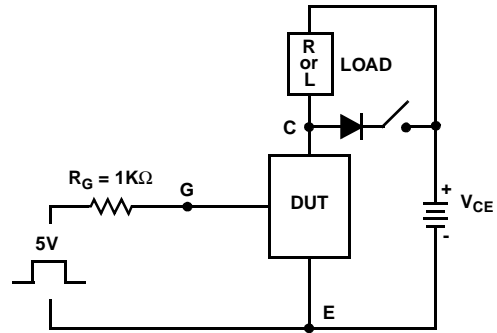


Figure 18.  $t_{ON}$  and  $t_{OFF}$  Switching Test Circuit

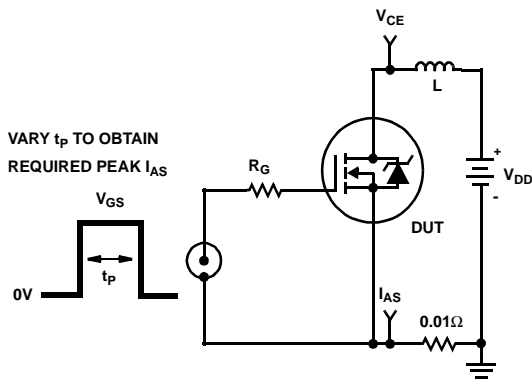


Figure 19. Energy Test Circuit

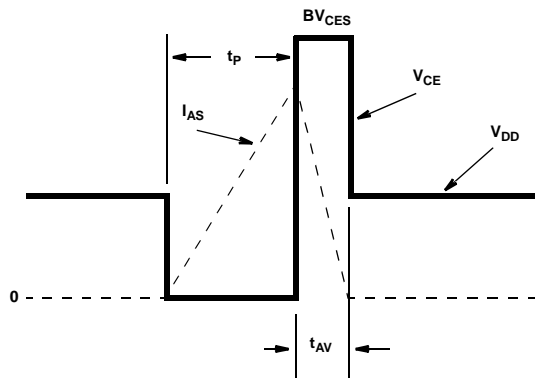






Figure 20. Energy Waveforms



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CTL™	IntelliMAX™	 ™	TINYOPTO™
Current Transfer Logic™	ISOPLANAR™	Saving our world, 1mW/W/kW at a time™	TinyPower™
DEUXPEED®	MegaBuck™	SignalWise™	TinyPwm™
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Datasheet Identification	Product Status	Definition
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